

MN1873265

Type	MN1873265		
ROM (×8-Bit)	32 K		
RAM (×8-Bit)	480		
Minimum Instruction Execution Time	0.5 μs at 2/3 frequency dividing (at 4.5 V to 5.5 V, 12 MHz)		
Interrupts	• RESET • External 0 • External 1 • Timer 0 • Timer 1 • Timer 2 • Remote Control • Line 21 • COSD		
Timer Counter	<p>Timer Counter 0 : 8-Bit × 1 Clock Source : 1/1, 1/4, 1/16, 1/64 of System Clock Interrupt Source : Overflow of Timer Counter 0</p> <p>Timer Counter 1 : 8-Bit × 1 Clock Source : 1/2, 1/16, 1/64, 1/256, 1/512 of System Clock Interrupt Source : Overflow of Timer Counter 1</p> <p>Time Base Counter Clock Source : 1/4096 of System Clock Interrupt Source : 1/1, 1/2, 1/4, 1/8 of Timer Counter 2</p> <p>Watchdog</p>		
I/O Pins	I/O	21	• Common use 3
	Input	1	• Common use 1
	High Voltage Output	7	• Nch Open-Drain (Breakdown Voltage 12 V) . 7
A/D Inputs	5-Bit × 7ch (without S/H)		
PWM	14-Bit × 1ch (Repetition Cycle 16 μs, at 12 MHz), 8-Bit × 8ch (Repetition Cycle 32 μs, at 12 MHz), 7-Bit × 1ch (Repetition Cycle 16 μs, at 12 MHz)		
Special Ports	Remote Control Reception		
CRTC	Single OSD built-in (Caption OSD 12 × 26 dots 176 letters)		
Notes	Remote Control Data Detection Circuit built-in		
Package	SDIP064-P-0750		

Electrical Characteristics

A/D Converter Characteristics

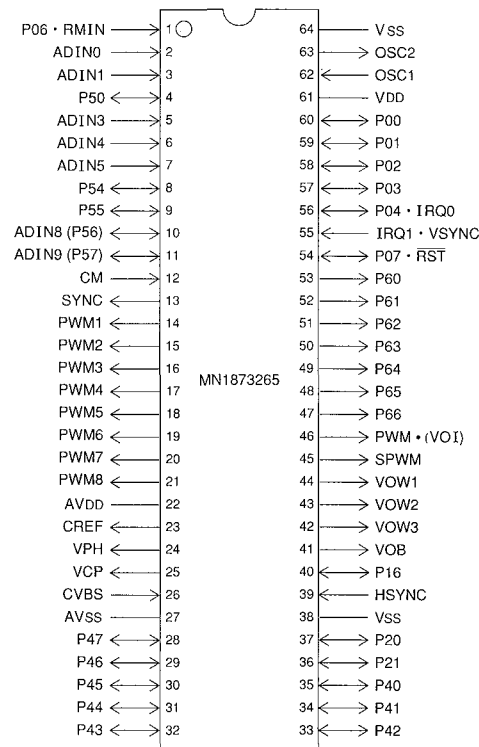
Parameter	Symbol	Condition	Limit			Unit
			min	typ	max	
A/D Conversion Time	TAD	fosc = 12 MHz	9			μs
Analog Input Voltage	VAD		VSS		VDD	V

(Ta = -20 °C to +70 °C, VDD = 5.0 V, VSS = 0 V)

Support Tool

In-Circuit Emulator	PX-ICE1870 / 80 + PX-PRB1876476
EPROM built-in Type	Type MN18P76476
	ROM (× 8-Bit) 64 K
	RAM (× 8-Bit) 928
	Minimum Instruction Execution Time 0.5 μs (at 4.5 V to 5.5 V, 12 MHz)
	Package SDIP064-P-0750

Pin Assignment



SDIP064-P-0750

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